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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	10MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	14
Program Memory Size	1KB (1K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8pe003hz010ec

GENERAL DESCRIPTION (Continued)

Both the 8-bit and 16-bit on-chip timers, with several user-selectable modes, administer real-time tasks such as counting/timing and I/O data communications.

Note: All signals with an overline are active Low. For example, $\overline{B/W}$, in which WORD is active Low; and $\overline{B/W}$, in which BYTE is active Low.

Power connections follow conventional descriptions below:

Connection	Circuit	Device
Power	V _{CC}	V _{DD}
Ground	GND	V _{SS}

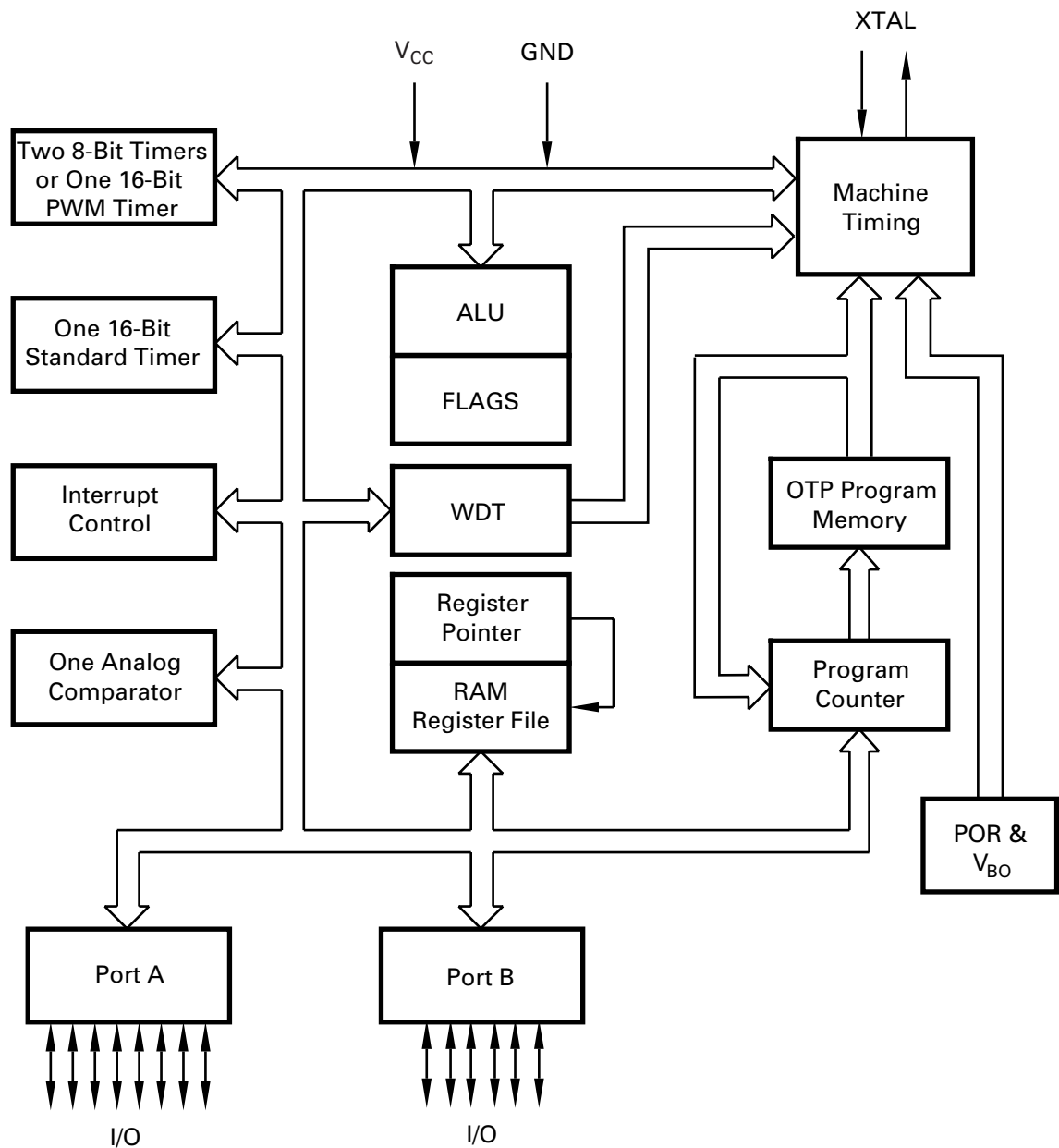


Figure 1. Functional Block Diagram

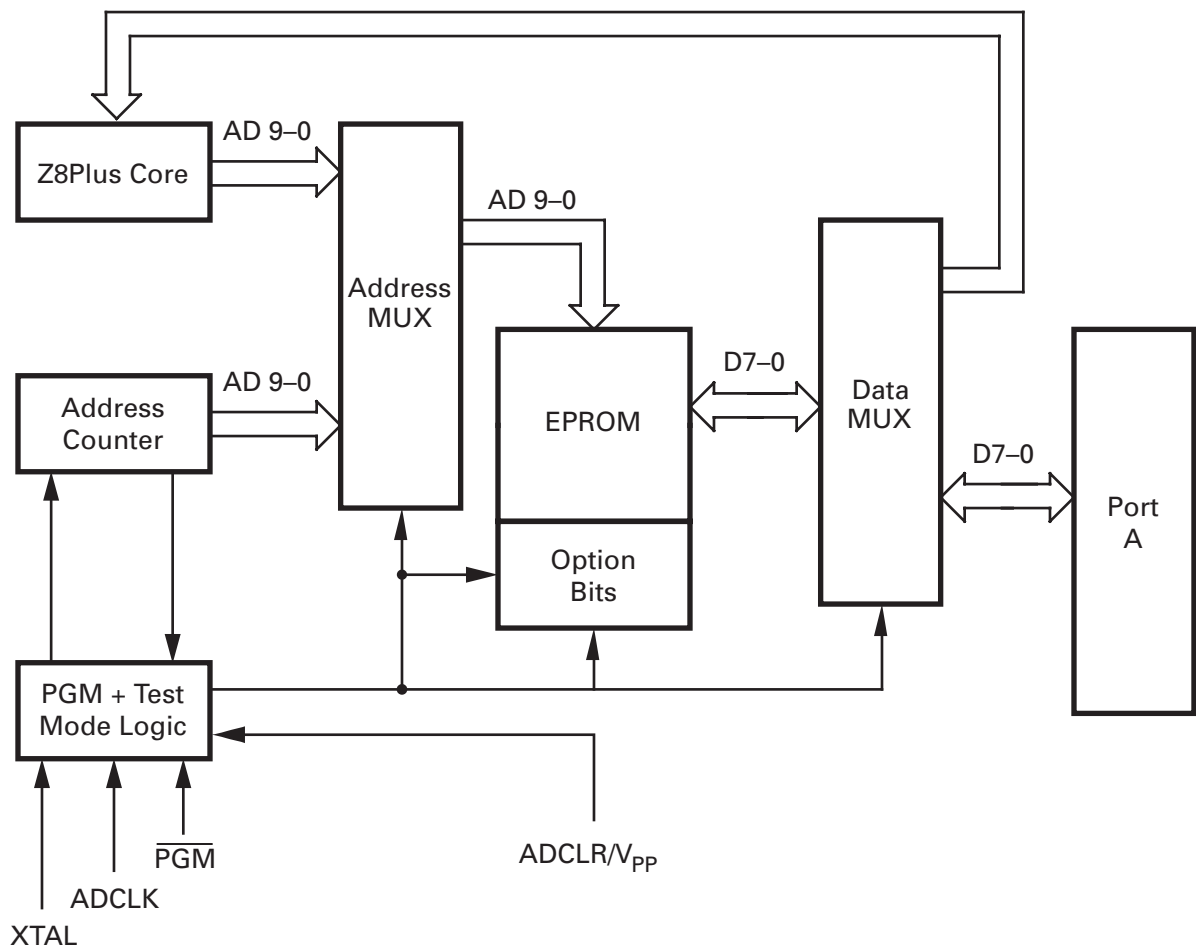


Figure 2. EPROM Programming Mode Block Diagram

PIN DESCRIPTION

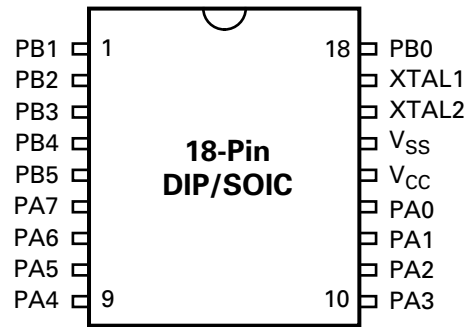


Figure 3. 18-Pin DIP/SOIC Pin Identification

Table 1. Standard Programming Mode

Pin #	Symbol	Function	Direction
1–5	PB1–PB5	Port B, Pins 1,2,3,4,5	Input/Output
6–9	PA7–PA4	Port A, Pins 7,6,5,4	Input/Output
10–13	PA3–PA0	Port A, Pins 3,2,1,0	Input/Output
14	V _{CC}	Power Supply	
15	V _{SS}	Ground	
16	XTAL2	Crystal Oscillator Clock	Output
17	XTAL1	Crystal Oscillator Clock	Input
18	PB0	Port B, Pin 0	Input/Output

ABSOLUTE MAXIMUM RATINGS

Parameter	Min	Max	Units	Note
Ambient Temperature under Bias	-40	+105	C	
Storage Temperature	-65	+150	C	
Voltage on any Pin with Respect to V_{SS}	-0.6	+7	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	-0.3	+7	V	
Voltage on PB5 Pin with Respect to V_{SS}	-0.6	$V_{DD}+1$	V	2
Total Power Dissipation		880	mW	
Maximum Allowable Current out of V_{SS}		40	mA	3
Maximum Allowable Current into V_{DD}		40	mA	3
Maximum Allowable Current into an Input Pin	-600	+600	μ A	4
Maximum Allowable Current into an Open-Drain Pin	-600	+600	μ A	5
Maximum Allowable Output Current Sunk by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sunk by Port A		40	mA	3
Maximum Allowable Output Current Sourced by Port A		40	mA	3
Maximum Allowable Output Current Sunk by Port B		40	mA	3
Maximum Allowable Output Current Sourced by Port B		40	mA	3

Notes:

1. Applies to all pins except the PB5 pin and where otherwise noted.
2. There is no input protection diode from pin to V_{DD} .
3. Peak Current. Do not exceed 25mA average current in either direction.
4. Excludes XTAL pins.
5. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings can cause permanent damage to the device. This rating is a stress rating only. Functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period

can affect device reliability. Total power dissipation should not exceed 880 mW for the package. Power dissipation is calculated as follows:

$$\begin{aligned} \text{Total Power Dissipation} = & V_{DD} \times [I_{DD} - (\text{sum of } I_{OH})] \\ & + \text{sum of } [(V_{DD} - V_{OH}) \times I_{OH}] \\ & + \text{sum of } (V_{OL} \times I_{OL}) \end{aligned}$$

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Figure 7).

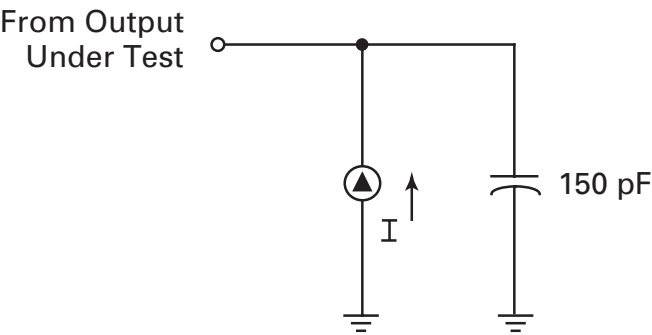


Figure 7. Test Load Diagram

CAPACITANCE

$T_A = 25^{\circ}\text{C}$, $V_{CC} = \text{GND} = 0\text{V}$, $f = 1.0\text{ MHz}$, unmeasured pins returned to GND.

Parameter	Min	Max
Input capacitance	0	12 pF
Output capacitance	0	12 pF
I/O capacitance	0	12 pF

Table 5. DC Electrical Characteristics (Continued)

T _A = 0°C to +70°C Standard Temperatures								
Sym	Parameter	V _{CC} ¹	Min	Max	Typical ² @ 25°C	Units	Conditions	Notes
I _{CC}	Supply Current	3.0V		2.5	2.0	mA	@ 10 MHz	5,6
		5.5V		6.0	3.5	mA	@ 10 MHz	5,6
I _{CC1}	Standby Current	3.0V		2.0	1.0	mA	HALT mode V _{IN} = 0V, V _{CC} @ 10 MHz	5,6
		5.5V		4.0	2.5	mA	HALT mode V _{IN} = 0V, V _{CC} @ 10 MHz	5,6
I _{CC2}	Standby Current			500	150	nA	STOP mode V _{IN} = 0V, V _{CC}	7

Notes:

1. The V_{CC} voltage specification of 3.0V guarantees 3.0V; the V_{CC} voltage specification of 5.5V guarantees 5.0V $\pm 0.5V$.
2. Typical values are measured at $V_{CC} = 3.3V$ and $V_{CC} = 5.0V$; $V_{SS} = 0V = GND$.
3. For the analog comparator input when the analog comparator is enabled.
4. No protection diode is provided from the pin to V_{CC} . External protection is recommended.
5. All outputs are unloaded and all inputs are at the V_{CC} or V_{SS} level.
6. $CL1 = CL2 = 22\text{ pF}$.
7. Same as note 5, except inputs are at V_{CC} .

Z8PLUS CORE

The device is based on the ZiLOG Z8Plus Core Architecture. This core is capable of addressing up to 64KB of program memory and 4 KB of RAM. Register RAM is accessed as either 8- or 16-bit registers using a combination of 4-, 8-, and 12-bit addressing modes. The architecture supports

up to 15 vectored interrupts from external and internal sources. The processor decodes 44 CISC instructions using 6 addressing modes. See the [Z8Plus User's Manual](#) for more information.

RESET

This section describes the Z8Plus reset conditions, reset timing, and register initialization procedures. Reset is generated by the Voltage Brown-Out/Power-On Reset (VBO/POR), Watch-Dog Timer (WDT), and Stop-Mode Recovery (SMR).

A system reset overrides all other operating conditions and puts the Z8Plus device into a known state. To initialize the chip's internal logic, the POR device counts 64 internal clock cycles after the oscillator stabilizes. The control registers and ports are not reset to their default conditions after wakeup from a STOP mode or WDT time-out.

During $\overline{\text{RESET}}$, the value of the program counter is 0020H. The I/O ports and control registers are configured to their

default reset state. Resetting the device does not affect the contents of the general-purpose registers.

The $\overline{\text{RESET}}$ circuit initializes the control and peripheral registers, as shown in Table 8. Specific reset values are indicated by a 1 or a 0, while bits whose states are unchanged or unknown from Power-Up are indicated by the letter U.

Program execution starts 10 External Crystal (XTAL) clock cycles after the POR delay. The initial instruction fetch is from location 0020H. Figure 9 indicates reset timing.

After a reset, the first routine executed must be one that initializes the TCTLHI control register to the required system configuration. This activity is followed by initialization of the remaining control registers.

Table 8. Control and Peripheral Registers*

Register (HEX)	Register Name	Bits								Comments
		7	6	5	4	3	2	1	0	
FF	Stack Pointer	0	0	U	U	U	U	U	U	Stack pointer is not affected by $\overline{\text{RESET}}$.
FE	Reserved									
FD	Register Pointer	U	U	U	U	0	0	0	0	Register pointer is not affected by $\overline{\text{RESET}}$.
FC	Flags	U	U	U	U	U	U	*	*	Only WDT & SMR flags are affected by $\overline{\text{RESET}}$.
FB	Interrupt Mask	0	0	0	0	0	0	0	0	All interrupts masked by $\overline{\text{RESET}}$.
FA	Interrupt Request	0	0	0	0	0	0	0	0	All interrupt requests cleared by $\overline{\text{RESET}}$.
F9–F0	Reserved									
EF–E0	Virtual Copy									Virtual copy of the current working register set.
DF–D8	Reserved									
D7	Port B Special Function	0	0	0	0	0	0	0	0	Deactivates all port special functions after $\overline{\text{RESET}}$.
D6	Port B Directional Control	0	0	0	0	0	0	0	0	Defines all bits as inputs in PortB after $\overline{\text{RESET}}$.
D5	Port B Output	U	U	U	U	U	U	U	U	Output register not affected by $\overline{\text{RESET}}$.

Note: *The SMR and WDT flags are set to indicate the source of the $\overline{\text{RESET}}$.

IREQ SOFTWARE INTERRUPT GENERATION

IREQ can be used to generate software interrupts by specifying IREQ as the destination of any instruction referencing the Z8Plus Standard Register File. These software interrupts (SWI) are controlled in the same manner as hardware generated requests. In other words, the IMASK controls the enabling of each SWI.

To generate a SWI, the request bit in IREQ is set by the following statement:

```
OR IREQ, #NUMBER
```

The immediate data variable, **NUMBER**, has a 1 in the bit position corresponding to the required level of SWI. For example, an SWI must be issued when an IREQ5 occurs. Bit 5 of **NUMBER** must have a value of 1.

```
OR IREQ, #00100000B
```

If the interrupt system is globally enabled, IREQ5 is enabled, and there are no higher priority requests pending, control is transferred to the service routine pointed to by the IREQ5 vector.

Note: Software may modify the IREQ register at any time. Care should be taken when using any instruction that modifies the IREQ register while interrupt sources are active. The software writeback always takes precedence over the hardware. If a software writeback takes place on the same cycle as an interrupt source tries to set an IREQ bit, the new interrupt is lost.

Nesting of Vectored Interrupts

Nesting vectored interrupts allows higher priority requests to interrupt a lower priority request. To initiate vectored interrupt nesting, perform the following steps during the interrupt service routine:

- PUSH the old IMASK on the stack
- Load IMASK with a new mask to disable lower priority interrupts
- Execute an EI instruction
- Proceed with interrupt processing
- Execute a DI instruction after processing is complete
- Restore the IMASK to its original value by POPing the previous mask from the stack
- Execute IRET

Depending on the application, some simplification of the above procedure may be possible.

RESET Conditions

The IMASK and IREQ registers initialize to 00h on RESET.

PROGRAMMABLE OPTIONS

EPROM Protect. When selecting the DISABLE EPROM PROTECT/ENABLE TESTMODE option, the user can read the software code in the program memory. ZiLOG's internal factory test mode, or any of the standard test mode methods, are useful for reading or verifying the code in the microcontroller when using an EPROM programmer. If the user should select the ENABLE EPROM PROTECT/DISABLE TESTMODE option, it is not possible to read the code using a tester, programmer, or any other standard method. As a result, ZiLOG is unable to test the EPROM memory at any time after customer delivery.

This option bit only affects the user's ability to read the code and has no effect on the operation of the part in an application. ZiLOG tests the EPROM memory before customer delivery whether or not the ENABLE EPROM PROTECT/DISABLE TESTMODE option is selected; ZiLOG provides a standard warranty for the part.

System Clock Source. When selecting the RC OSCILLATOR ENABLE option, the oscillator circuit on the microcontroller is configured to work with an external RC circuit. When selecting the Crystal/Other Clock Source option, the oscillator circuit is configured to work with an external crystal, ceramic resonator, or LC oscillator.

STOP MODE OPERATION

The STOP mode provides the lowest possible device standby current. This instruction turns off the on-chip oscillator and internal system clock.

To enter the STOP mode, the Z8Plus only requires a STOP instruction. It is *not* necessary to execute a NOP instruction immediately before the STOP instruction.

```
6F  STOP  ;enter STOP mode
```

The STOP mode is exited by any one of the following resets: POR or a Stop-Mode Recovery source. At reset generation, the processor always restarts the application program at address 0020H, and the STOP mode flag is set. Reading the STOP mode flag does not clear it. The user must clear the STOP mode flag with software.

Note: Failure to clear the STOP mode flag can result in undefined behavior.

The Z8Plus provides a dedicated Stop-Mode Recovery (SMR) circuit. In this case, a low-level applied to input pin PB0 (I/O Port B, bit 0) triggers an SMR. To use this mode, pin PB0 must be configured as an input and the special function selected before the STOP mode is entered. The Low level on PB0 must be held for a minimum pulse width T_{WSM} . Program execution starts at address 20h, after the POR delay.

Notes: 1. The PB0 input, when used for Stop-Mode Recovery, does not initialize the control registers.

The STOP mode current (I_{CC2}) is minimized when:

- V_{CC} is at the low end of the device's operating range
- Output current sourcing is minimized
- All inputs (digital and analog) are at the Low or High rail voltages

2. For detailed information about flag settings, see the [Z8Plus User's Manual](#).

OSCILLATOR OPERATION

The Z8Plus MCU uses a Pierce oscillator with an internal feedback resistor (Figure 14). The advantages of this circuit are low-cost, large output signal, low-power level in the crystal, stability with respect to V_{CC} and temperature, and low impedances (not disturbed by stray effects).

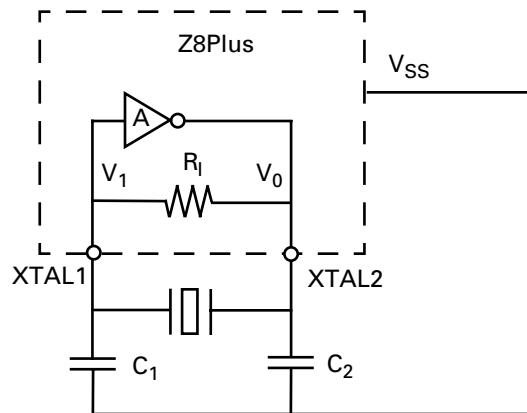


Figure 14. Pierce Oscillator with Internal Feedback Circuit

One drawback to the Pierce oscillator is the requirement for high gain in the amplifier to compensate for feedback path losses. The oscillator amplifies its own noise at start-up until it settles at the frequency that satisfies the gain/phase requirements. $A \times B = 1$; where $A = V_O/V_I$ is the gain of the amplifier, and $B = V_I/V_O$ is the gain of the feedback element. The total phase shift around the loop is forced to 0 (360 degrees). V_{IN} must be in phase with itself; therefore, the amplifier/inverter provides a 180-degree phase shift, and the feedback element is forced to provide the other 180-degree phase shift.

R_1 is a resistive component placed from output to input of the amplifier. The purpose of this feedback is to bias the amplifier in its linear region and provide the start-up transition.

Capacitor C_2 , combined with the amplifier output resistance, provides a small phase shift. It also provides some attenuation of overtones.

Capacitor C_1 , combined with the crystal resistance, provides an additional phase shift.

Start-up time may be affected if C_1 and C_2 are increased dramatically in size. As C_1 and C_2 increase, the start-up time

increases until the oscillator reaches a point where it ceases to operate.

For fast and reliable oscillator start-up over the manufacturing process range, the load capacitors should be sized as low as possible without resulting in overtone operation.

Layout

Traces connecting crystal, caps, and the Z8Plus oscillator pins should be as short and wide as possible to reduce parasitic inductance and resistance. The components (caps, the crystal, and resistors) should be placed as close as possible to the oscillator pins of the Z8Plus.

The traces from the oscillator pins of the integrated circuit (IC) and the ground side of the lead caps should be guarded from all other traces (clock, V_{CC} , address/data lines, and system ground) to reduce cross talk and noise injection. Guarding is usually accomplished by keeping other traces and system ground trace planes away from the oscillator circuit, and by placing a Z8Plus device V_{SS} ground ring around the traces/components. The ground side of the oscillator lead caps should be connected to a single trace to the Z8Plus device V_{SS} (GND) pin. It should not be shared with any other system-ground trace or components except at the Z8Plus device V_{SS} pin. The objective is to prevent differential system ground noise injection into the oscillator (Figure 15).

Indications of an Unreliable Design

There are two major indicators that are used in working designs to determine their reliability over full lot and temperature variations. They are:

Start-Up Time. If start-up time is excessive, or varies widely from unit to unit, there is probably a gain problem. To fix the problem, the C_1 and C_2 capacitors require reduction. The amplifier gain is either not adequate at frequency, or the crystal R 's are too large.

Output Level. The signal at the amplifier output should swing from ground to V_{CC} to indicate adequate gain in the amplifier. As the oscillator starts up, the signal amplitude grows until clipping occurs. At that point, the loop gain is effectively reduced to unity, and constant oscillation is achieved. A signal of less than 2.5 volts peak-to-peak is an indication that low gain can be a problem. Either C_1 or C_2 should be made smaller, or a low-resistance crystal should be used.

OSCILLATOR OPERATION (Continued)

Circuit Board Design Rules

The following circuit board design rules are suggested:

- To prevent induced noise, the crystal and load capacitors should be physically located as close to the Z8Plus as possible.
- Signal lines should not run parallel to the clock oscillator inputs. In particular, the crystal input circuitry

and the internal system clock output should be separated as much as possible.

- V_{CC} power lines should be separated from the clock oscillator input circuitry.
- Resistivity between XTAL1 or XTAL2 (and the other pins) should be greater than 10 meg-Ohms.

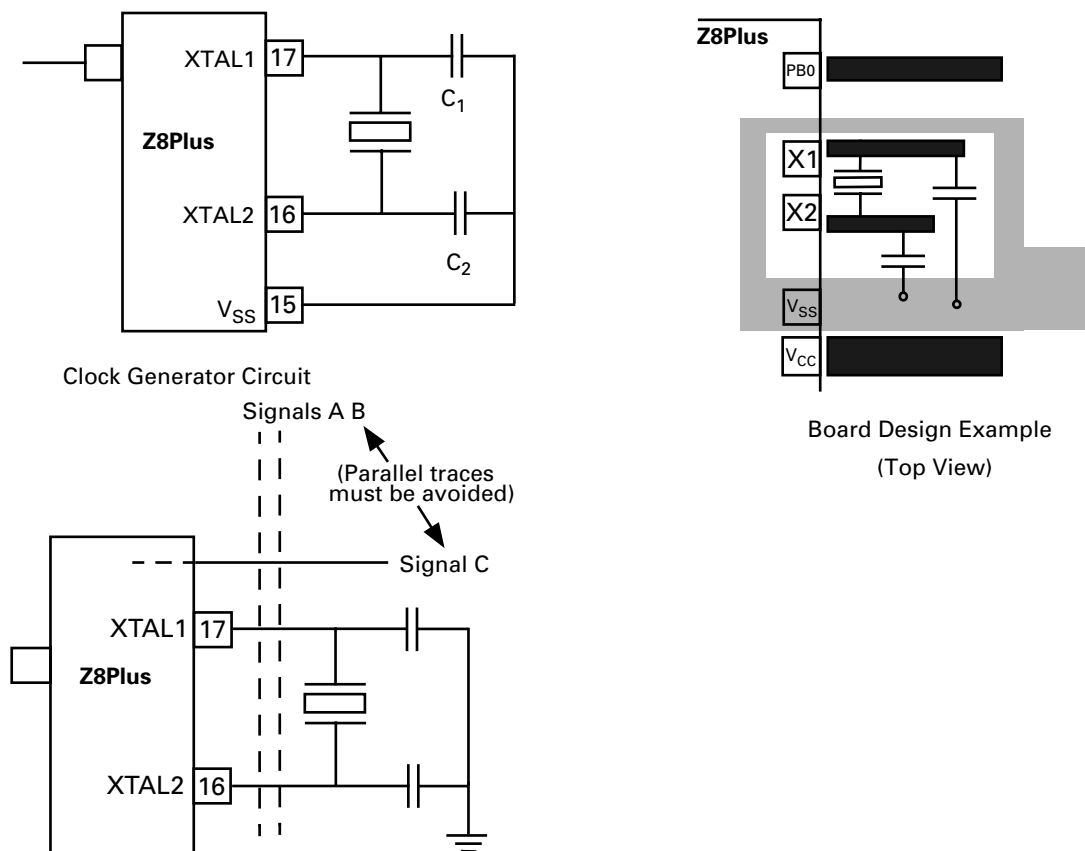


Figure 15. Circuit Board Design Rules

Crystals and Resonators

Crystals and ceramic resonators (Figure 16) should exhibit the following characteristics to ensure proper oscillation:

Crystal Cut	AT (crystal only)
Mode	Parallel, fundamental mode
Crystal Capacitance	<7pF
Load Capacitance	10pF < CL < 220 pF, 15 typical
Resistance	100 Ohms maximum

Depending on the operation frequency, the oscillator may require additional capacitors, C_1 and C_2 , as illustrated in Figure 16 and Figure 17. The capacitance values are dependent on the manufacturer's crystal specifications.

If a timer pair is defined to operate as a single 16-bit entity, the entire 16-bit value must reach 0 before an interrupt is generated. In this case, a single interrupt is generated, and the interrupt corresponds to the even 8-bit timer.

Example: Timers T2 and T3 are cascaded to form a single 16-bit timer. The interrupt for the combined timer is defined to be generated by timer T2 rather than T3. When a timer pair is specified to act as a single 16-bit timer, the even timer registers in the pair (timer T0 or T2) is defined to hold the timer's least significant byte. In contrast, the odd timer in the pair holds the timer's most significant byte.

In parallel with the posting of the interrupt request, the interrupting timer's count value is initialized by copying the contents of the auto-initialization value register to the count value register.

Note: Any time that a timer pair is defined to act as a single 16-bit timer, the auto-reload function is performed automatically.

All 16-bit timers continue counting while their interrupt requests are active and operate independently of each other.

If interrupts are disabled for a long period of time, it is possible for the timer to decrement to 0 again before its initial interrupt is responded to. This condition is termed a degenerate case, and hardware is not required to detect it.

When the timer control register is written, all timers that are enabled by the WRITE begin counting from the value in the count register. In this case, an auto-initialization is not performed. All timers can receive an internal clock source input only. Each enabled timer is updated every 8th XTAL clock cycle.

If T0 and T1 are defined to work independently, then each works as an 8-bit timer with a single auto-initialization register (T0ARLO for T0, and T1ARLO for T1). Each timer asserts its predefined interrupt when it times out, optionally performing the auto-initialization function. If T0 and T1 are cascaded to form a single 16-bit timer, then the single 16-bit timer is capable of performing as a Pulse-Width Modulator (PWM). This timer is referred to as T01 to distinguish it as having special functionality that is not available when T0 and T1 act independently.

When T01 is enabled, it can use a pair of 16-bit auto-initialization registers. In this mode, one 16-bit auto-initial-

ization value is composed of the concatenation of T1ARLO and T0ARLO. The second auto-initialization value is composed of the concatenation of T1ARHI and T0ARHI. When T01 times out, it alternately initializes its count value using the Low auto-init pair, followed by the High auto-init pair. This functionality corresponds to a PWM. That is, the T1 interrupt defines the end of the High section of the waveform, and the T0 interrupt marks the end of the Low portion of the PWM waveform.

The PWM begins counting with whatever data is held in the count registers. After this value expires, the first reload depends on the state of the PB1 pin if T_{OUT} mode is selected. Otherwise, the Low value is applied first.

After the auto-initialization is completed, decrementing occurs for the number of counts defined by the PWM_LO registers. When decrementing again reaches 0, the T0 interrupt is asserted; and auto-init using the PWM_HI registers occurs. Decrementing occurs for the number of counts defined by the PWM_HI registers until reaching 0. From there, the T1 interrupt IRQ2 is asserted, and the cycle begins again.

The internal timers can be used to trigger external events by toggling the PB1 output when generating an interrupt. This functionality can only be achieved in conjunction with the port unit defining the appropriate pin as an output signal with the timer output special function enabled. In this mode, the port output is toggled when the timer count reaches 0, and continues toggling each time that the timer times out.

T_{OUT} Mode

The PortB special function register PTBSFR (0D7H; Figure 23) is used in conjunction with the Port B directional control register PTBDIR (0D6; Figure 24) to configure PB1 for T_{OUT} operation for T0. In order for T_{OUT} to function, PB1 must be defined as an output line by setting PTBDIR bit 1 to 1. Configured in this way, PB1 is capable of being a clock output for T0, toggling the PB1 output pin on each T0 time-out.

At end-of-count, the interrupt request line (IRQ0), clocks a toggle flip-flop. The output of this flip-flop drives the T_{OUT} line, PB1. In all cases, when T0 reaches its end-of-count, T_{OUT} toggles to its opposite state (Figure 25). If, for example, T0 is in Continuous Counting Mode, T_{OUT} exhibits a 50-percent duty cycle output. If the timer pair is selected (T01) as a PWM, the duty cycle depends on the High and Low reload values. At the end of each High time, PB1 toggles Low. At the end of each Low time, PB1 toggles HI.

TIMERS (Continued)

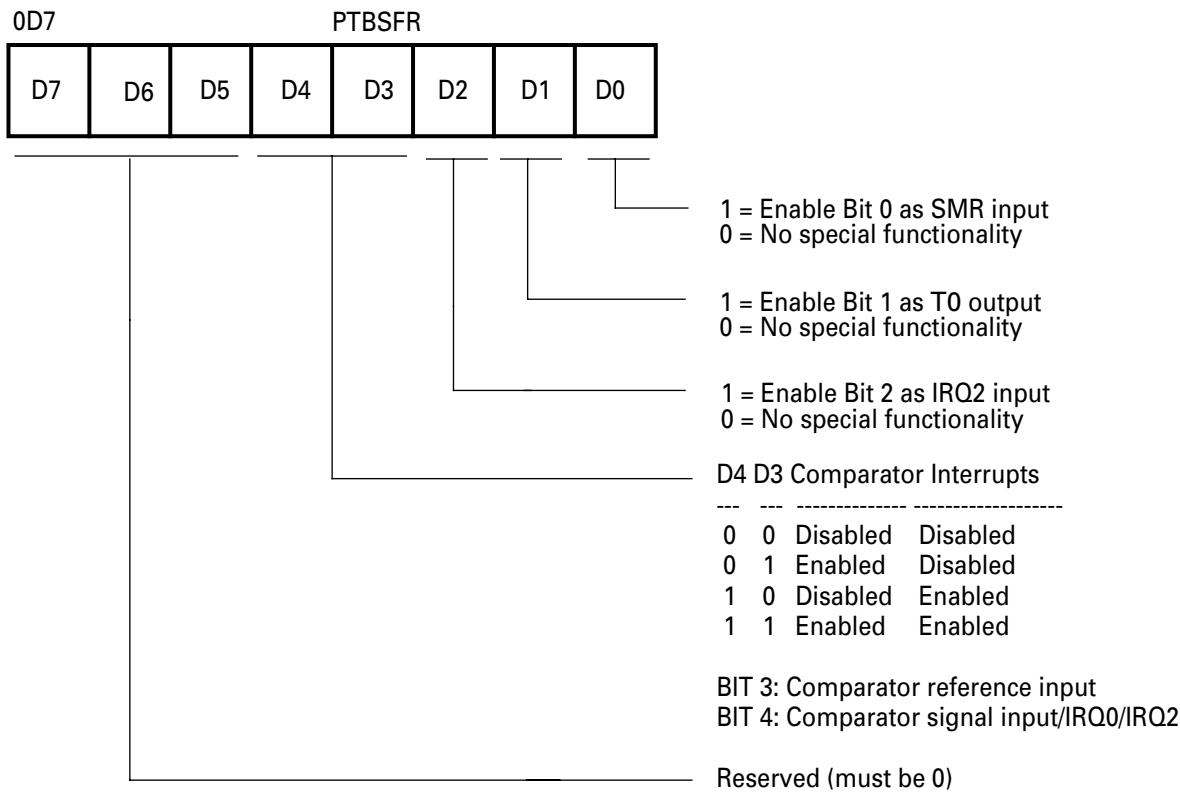


Figure 23. PortB Special Function Register

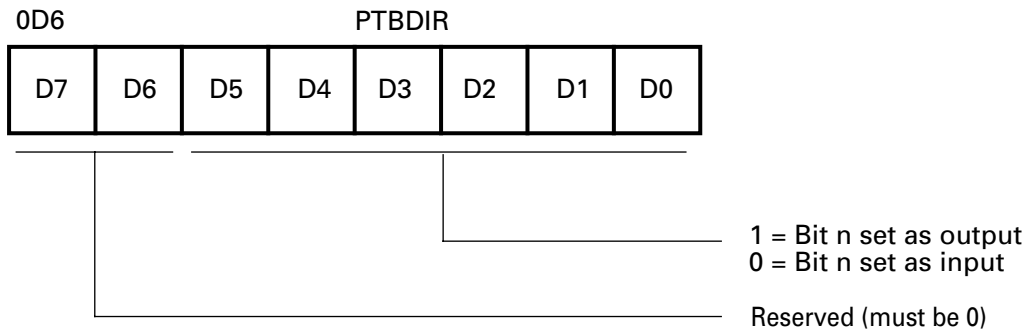


Figure 24. Port B Directional Control Register

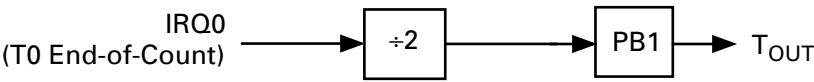


Figure 25. Timer T0 Output Through T_{OUT}

RESET CONDITIONS

After a $\overline{\text{RESET}}$, the timers are disabled. See Table 8 for timer control, value, and auto-initialization register status after $\overline{\text{RESET}}$.

I/O PORTS

The Z8Plus dedicates 14 lines to input and output. These lines are grouped into two ports known as Port A and Port B. Port A is an 8-bit port, bit programmable as either inputs or outputs. Port B can be programmed to provide either standard input/output, or the following special functions: T0 output, comparator input, SMR input, and external interrupt inputs.

All pins except PB5 include push-pull CMOS outputs. In addition, the outputs of Port A on a bit-wise basis can be configured for open-drain operation. The ports operate on a bit-wise basis. As such, the register values for/at a given bit position only affect the bit in question.

Each port is defined by a set of four control registers (Figure 26).

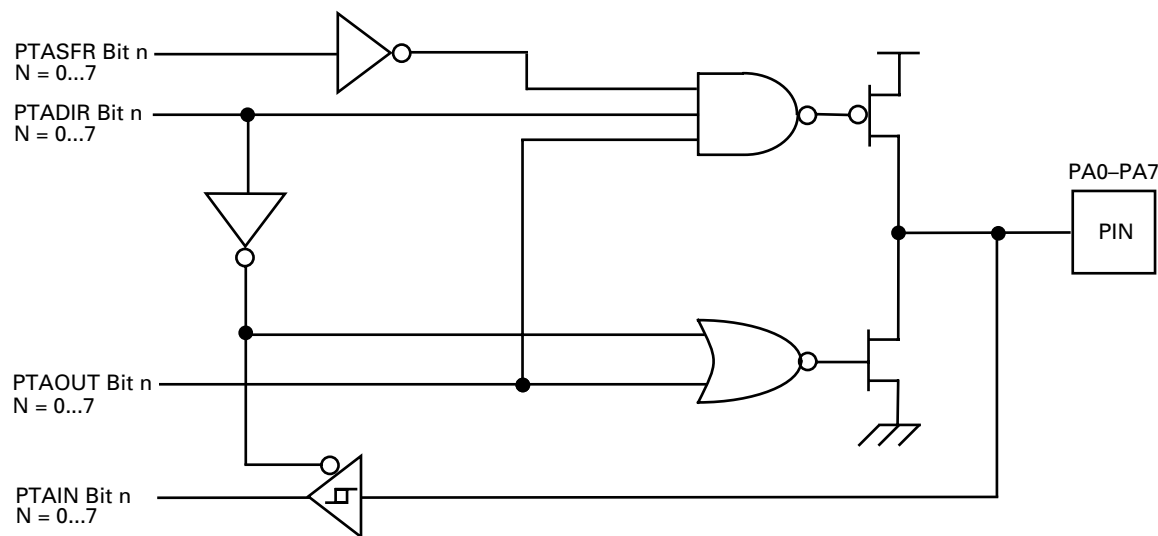


Figure 26. Port A Configuration with Open-Drain Capability and Schmitt-Trigger

Directional Control and Special Function Registers

Each port on the Z8Plus features a dedicated directional control register that determines (on a bit-wise basis) if a given port bit operates as input or output.

Each port on the Z8Plus features a special function register (SFR) that, in conjunction with the directional control register, implements (on a bit-by-bit basis) any special functionality that can be defined for each particular port bit.

Table 14. I/O Ports Registers

Register	Address	Identifier
Port B Special Function	0D7H	PTBSFR
Port B Directional Control	0D6H	PTBDIR
Port B Output Value	0D5H	PTBOUT
Port B Input Value	0D4H	PTBIN
Port A Special Function	0D3H	PTASFR
Port A Directional Control	0D2H	PTADIR
Port A Output Value	0D1H	PTAOUT
Port A Input Value	0D0H	PTAIN

Input and Output Value Registers

Each port features an Output Value Register and an input value register. For port bits configured as an input by means of the directional control register, the input value register

PORT B—PIN 1 CONFIGURATION

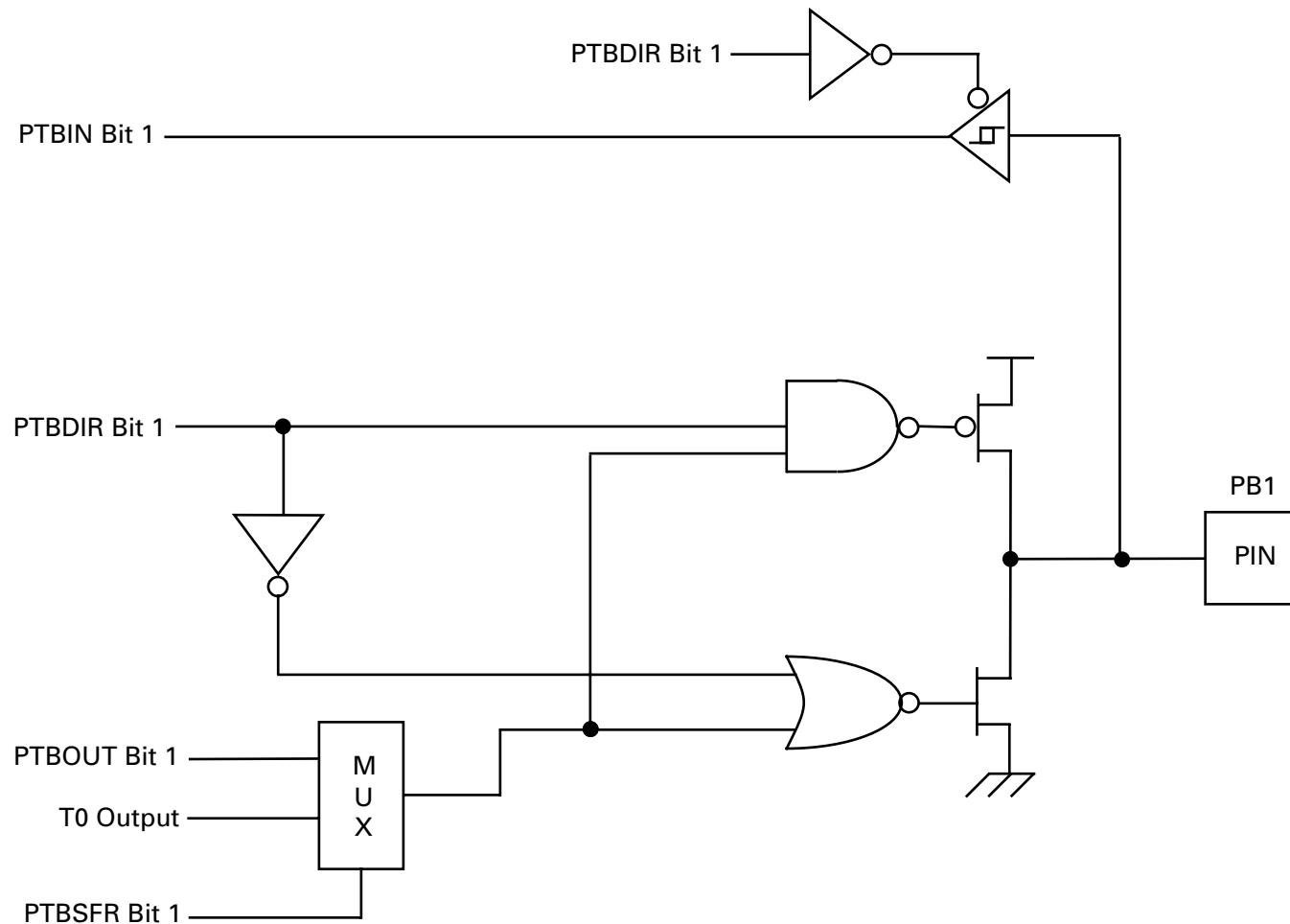


Figure 35. Port B Pin 1 Diagram

I/O PORT RESET CONDITIONS

Full Reset

Port A and Port B output value registers are not affected by $\overline{\text{RESET}}$.

On $\overline{\text{RESET}}$, the Port A and Port B directional control registers are cleared to all zeros, which defines all pins in both ports as inputs.

On $\overline{\text{RESET}}$, the directional control registers redefine all pins as inputs, and the Port A and Port B input value registers

overwrites the previously held data with the current sample of the input pins.

On $\overline{\text{RESET}}$, the Port A and Port B special function registers are cleared to 00h, which deactivates all port special functions.

Note: The SMR and WDT time-out events are *not* full device resets. The port control registers are not affected by either of these events.

ANALOG COMPARATOR

The device includes one on-chip analog comparator. Pin PB4 features a comparator front end. The comparator reference voltage is on pin PB3.

Comparator Description

The on-chip comparator can process an analog signal on PB4 with reference to the voltage on PB3. The analog function is enabled by programming the Port B special function register bits 3 and 4.

When the analog comparator function is enabled, bit 4 of the input register is defined as holding the synchronized output of the comparator, while bit 3 retains a synchronized sample of the reference input.

If the interrupts for PB4 are enabled when the comparator special function is selected, the output of the comparator generates interrupts.

COMPARATOR OPERATION

The comparator output reflects the relationship between the analog input to the reference input. If the voltage on the analog input is higher than the voltage on the reference input, then the comparator output is at a High state. If the voltage on the analog input is lower than the voltage on the reference input, then the analog output is at a Low state.

Comparator Definitions

V_{ICR}

The usable voltage range for the positive input and reference input is called the Comparator Input Common Mode Voltage Range (V_{ICR}).

Note: The comparator is not guaranteed to work if the input is outside of the V_{ICR} range.

V_{OFFSET}

The absolute value of the voltage between the positive input and the reference input required to make the comparator output voltage switch is the Comparator Input Offset Voltage (V_{OFFSET}).

I_{IO}

For the CMOS voltage comparator input, the input offset current (I_{IO}) is the leakage current of the CMOS input gate.

HALT Mode

The analog comparator is functional during HALT mode. If the interrupts are enabled, an interrupt generated by the comparator causes a return from HALT mode.

STOP Mode

The analog comparator is disabled during STOP mode. The comparator is powered down to prevent it from drawing any current.

Low Voltage Protection. An on-board Voltage Comparator checks that the V_{CC} is at the required level to ensure correct operation of the device. A reset is globally driven if V_{CC} is below the specified voltage (Low Voltage Protection).

The device functions normally at or above 3.0V under all conditions, and is guaranteed to function normally at supply voltages above the Low Voltage Protection trip point. Below 3.0V, the device functions normally until the Low Volt-

COMPARATOR OPERATION (Continued)

age Protection trip point (V_{LV}) is reached. The actual Low-Voltage Protection trip point is a function of process parameters.

Low-Voltage Protection is active in RUN and HALT modes only, but is disabled in STOP mode (Figure 42).

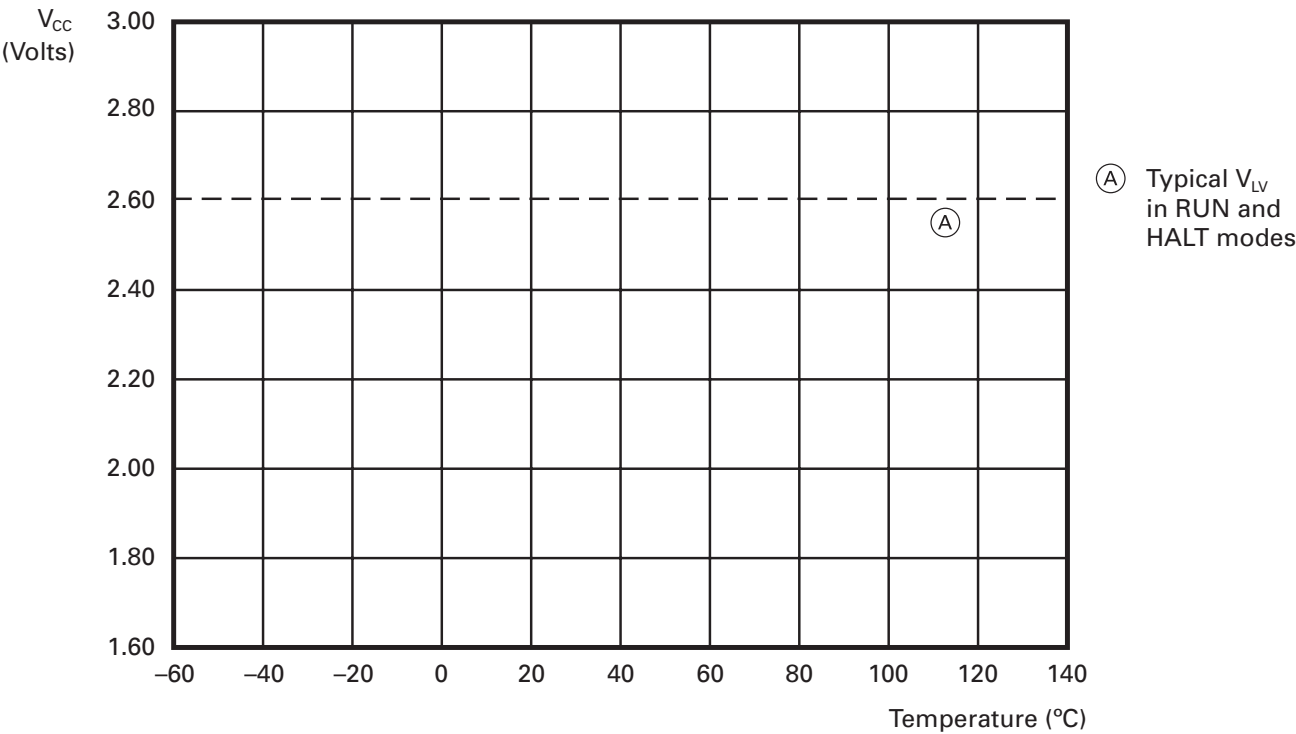


Figure 42. Typical Low Voltage Protection vs. Temperature

INPUT PROTECTION

All I/O pins feature diode input protection. There is a diode from the I/O pad to V_{CC} and V_{SS} (Figure 43).

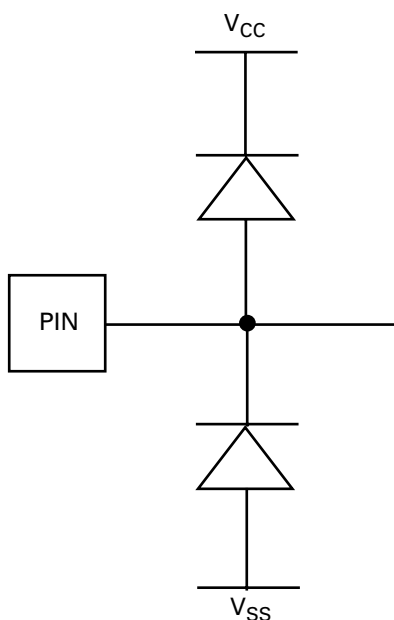


Figure 43. I/O Pin Diode Input Protection

However, the PB5 pin features only the input protection diode, from the pad to V_{SS} (Figure 44).

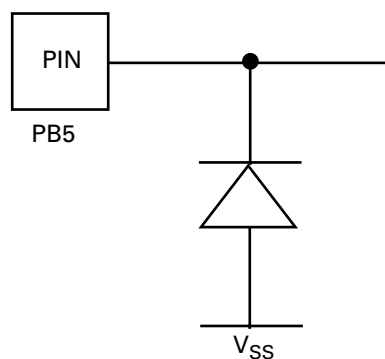
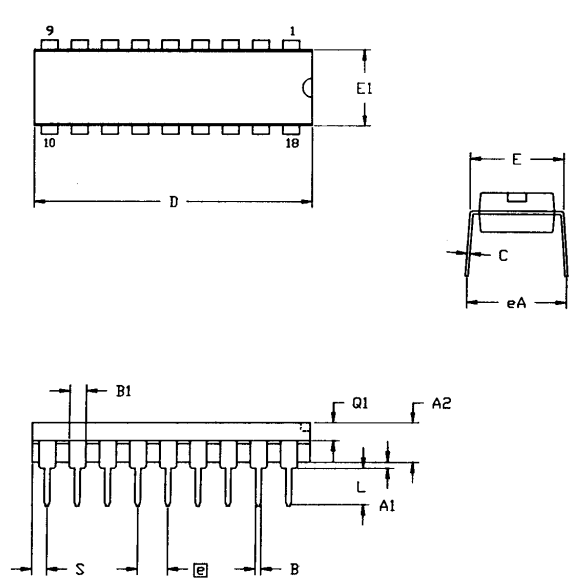


Figure 44. PB5 Pin Input Protection

The high-side input protection diode was removed on this pin to allow the application of high voltage during the OTP programming mode.

For better noise immunity in applications that are exposed to system EMI, a clamping diode to V_{SS} from this pin should be used to prevent entering the OTP programming mode or to prevent high voltage from damaging this pin.

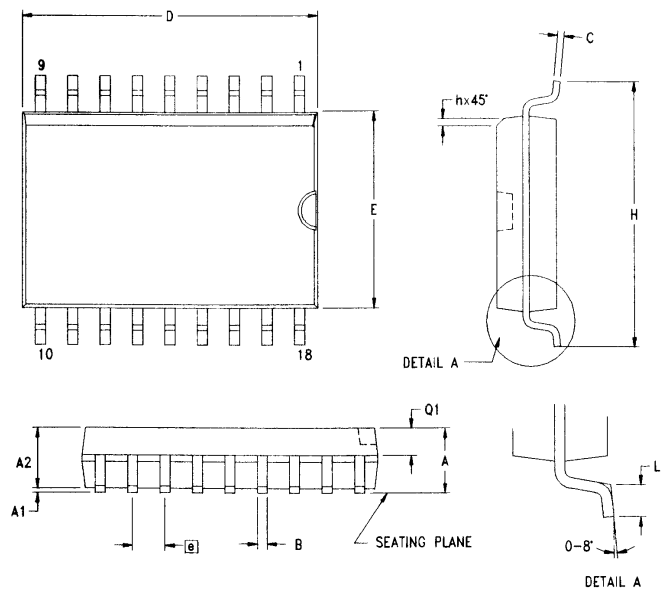
PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	0.81	.020	.032
A2	3.25	3.43	.128	.135
B	0.38	0.53	.015	.021
B1	1.14	1.65	.045	.065
C	0.23	0.38	.009	.015
D	22.35	23.37	.880	.920
E	7.62	8.13	.300	.320
E1	6.22	6.48	.245	.255
⌀	2.54 TYP		.100 TYP	
eA	7.87	8.89	.310	.350
L	3.18	3.81	.125	.150
Q1	1.52	1.65	.060	.065
S	0.89	1.65	.035	.065

CONTROLLING DIMENSIONS : INCH

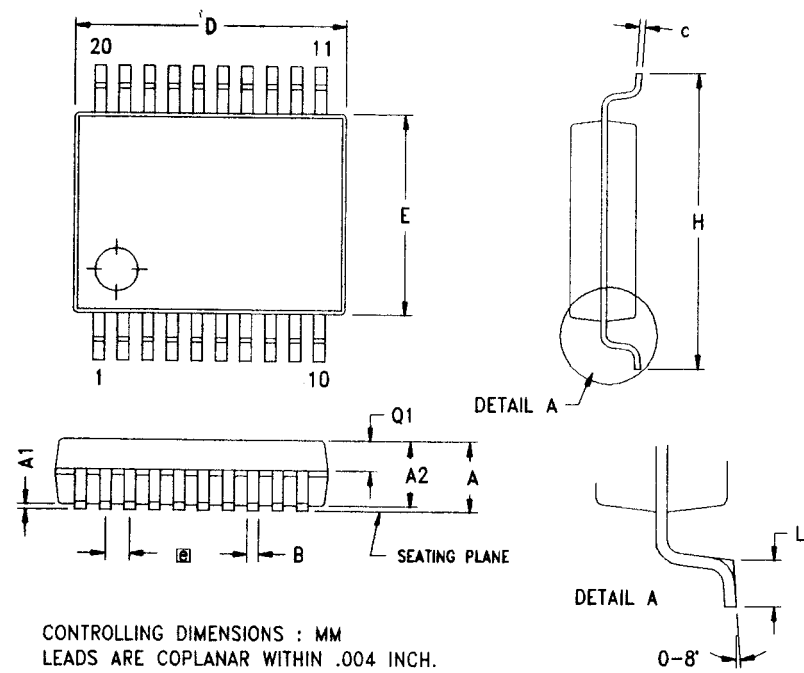
Figure 45. 18-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.65	0.094	0.104
A1	0.10	0.30	0.004	0.012
A2	2.24	2.44	0.088	0.096
B	0.36	0.46	0.014	0.018
C	0.23	0.30	0.009	0.012
D	11.40	11.75	0.449	0.463
E	7.40	7.60	0.291	0.299
⌀	1.27 TYP		0.050 TYP	
H	10.00	10.65	0.394	0.419
h	0.30	0.50	0.012	0.020
L	0.60	1.00	0.024	0.039
Q1	0.97	1.07	0.038	0.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 46. 18-Pin SOIC Package Diagram



SYMBOL	MILLIMETER			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.73	1.85	1.98	0.068	0.073	0.078
A1	0.05	0.13	0.21	0.002	0.005	0.008
A2	1.68	1.73	1.83	0.066	0.068	0.072
B	0.25	0.30	0.38	0.010	0.012	0.015
C	0.13	0.15	0.22	0.005	0.006	0.009
D	7.07	7.20	7.33	0.278	0.283	0.289
E	5.20	5.30	5.38	0.205	0.209	0.212
Ⓟ	0.65 TYP			0.0256 TYP		
H	7.65	7.80	7.90	0.301	0.307	0.311
L	0.56	0.75	0.94	0.022	0.030	0.037
Q1	0.74	0.78	0.82	0.029	0.031	0.032

Figure 47. 20-Pin SSOP Package Diagram